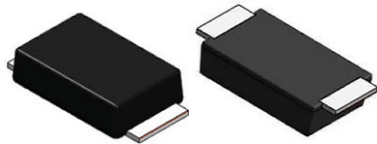


Hyperfast Rectifier, 3 A FRED Pt[®]

eSMP[®] Series



Top View

Bottom View

SlimSMAW (DO-221AD)



DESIGN SUPPORT TOOLS AVAILABLE



3D Models

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	3 A
V_R	100 V, 200 V
V_F at I_F	0.71 V
I_{FSM}	70 A
t_{rr} (typ.)	16 ns
T_J max.	175 °C
Package	SlimSMAW (DO-221AD)
Circuit configuration	Single

FEATURES

- Low profile package
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified, class 2 whisker test
- Compatible to SOD-128 package case outline
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE


RoHS
COMPLIANT
HALOGEN
FREE

DESCRIPTION / APPLICATIONS

For use in high frequency, freewheeling, DC/DC converters, PFC, and in snubber industrial, and automotive applications.

MECHANICAL DATA

Case: SlimSMAW (DO-221AD)

Molding compound meets UL 94 V-0 flammability rating halogen-free, RoHS-compliant

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B1022

Polarity: color band denotes the cathode end

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		100	V
			200	
Average rectified forward current	$I_{F(AV)}$ ⁽¹⁾	$T_C = 137$ °C	3	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25$ °C, 10 ms sine pulse wave	70	
Operating junction and storage temperatures	T_J, T_{Stg}		-55 to +175	°C

Note

⁽¹⁾ Mounted on infinite heatsink

ELECTRICAL SPECIFICATIONS ($T_J = 25$ °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100$ μ A	100	-	-	V
			200	-	-	
Forward voltage, per diode	V_F	$I_F = 3$ A	-	0.86	0.95	
		$I_F = 3$ A, $T_J = 150$ °C	-	0.71	0.79	
Reverse leakage current, per diode	I_R	$V_R = V_R$ rated	-	-	2	μ A
		$T_J = 150$ °C, $V_R = V_R$ rated	-	-	20	
Junction capacitance	C_T	$V_R = 200$ V	-	16	-	pF



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time	t _{rr}	I _F = 1.0 A, dI _F /dt = 50 A/μs, V _R = 30 V	-	22	-	ns	
		I _F = 1.0 A, dI _F /dt = 100 A/μs, V _R = 30 V	-	16	-		
		I _F = 0.5 A, I _R = 1A, I _{rr} = 0.25 A	-	-	30		
		T _J = 25 °C	-	18	-		
		T _J = 125 °C	-	30	-		
Peak recovery current	I _{RRM}	I _F = 3 A, dI _F /dt = 200 A/μs, V _R = 100 V	T _J = 25 °C	-	2.5	-	A
			T _J = 125 °C	-	4	-	
Reverse recovery charge	Q _{rr}	I _F = 3 A, dI _F /dt = 200 A/μs, V _R = 100 V	T _J = 25 °C	-	23	-	nC
			T _J = 125 °C	-	60	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C
Thermal resistance, junction to mount	R _{thJM} ⁽¹⁾	Infinite heatsink	-	12	15	°C/W
Thermal resistance, junction to ambient	R _{thJA}	Device mounted on FR4 PCB, 2 oz. standard footprint	-	120	150	
Marking device	VS-3EYH01HM3	Case style SlimSMAW (DO-221AD)	3H1			
	VS-3EYH02HM3		3H2			

Note

(1) Thermal resistance junction to mount follows JEDEC® 51-14 transient dual interface test method (TDIM)

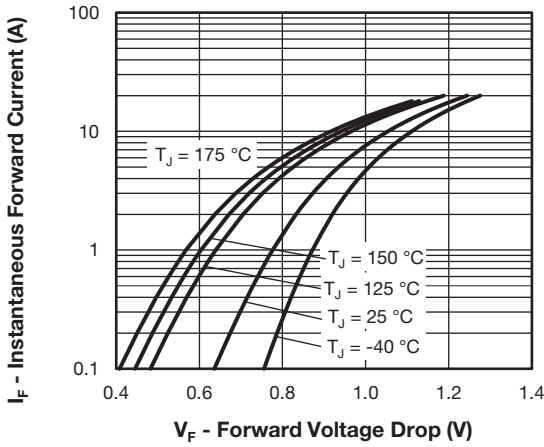


Fig. 1 - Typical Forward Voltage Drop Characteristics

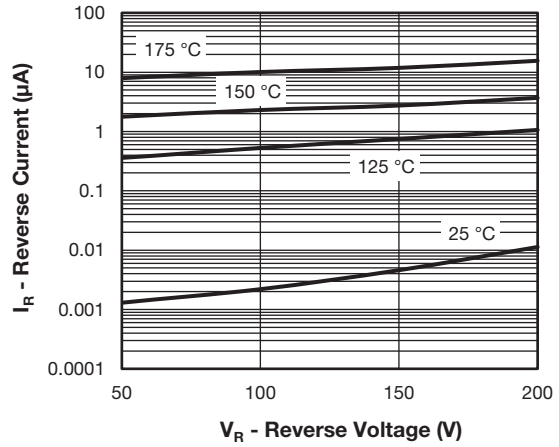


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

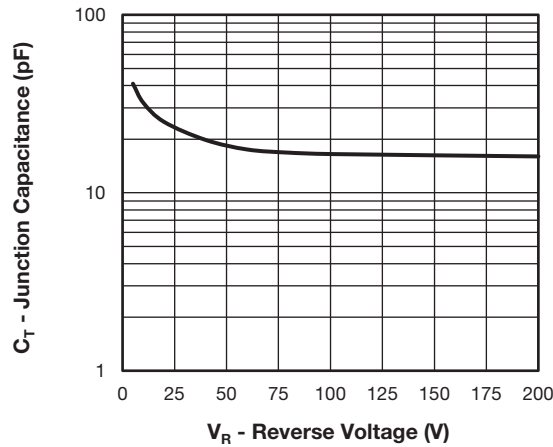


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

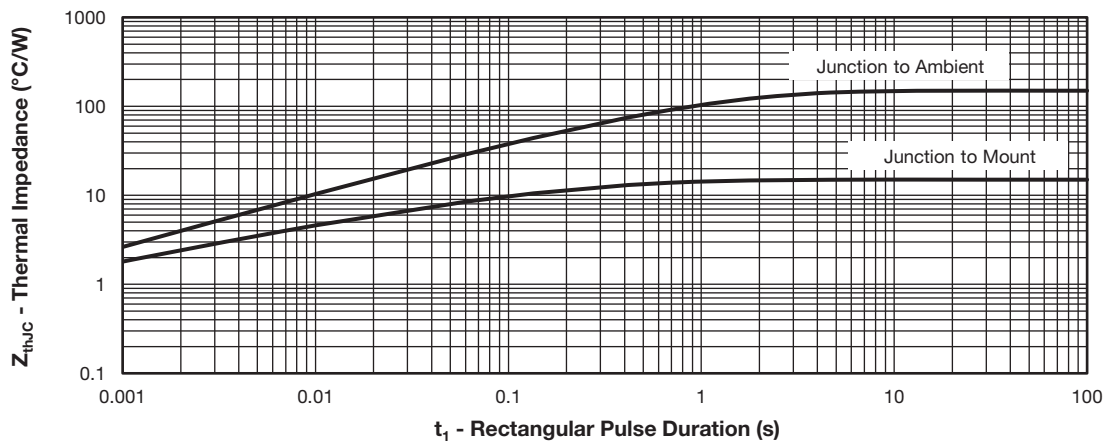


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

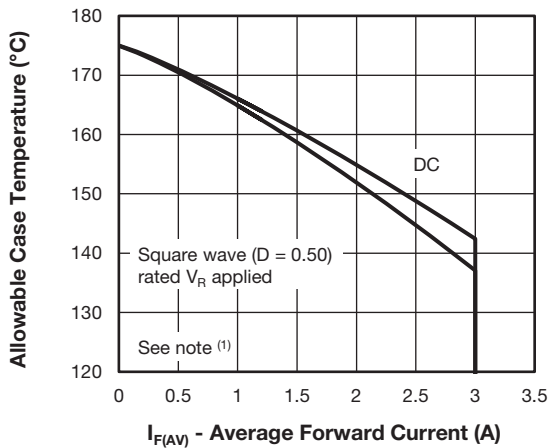


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

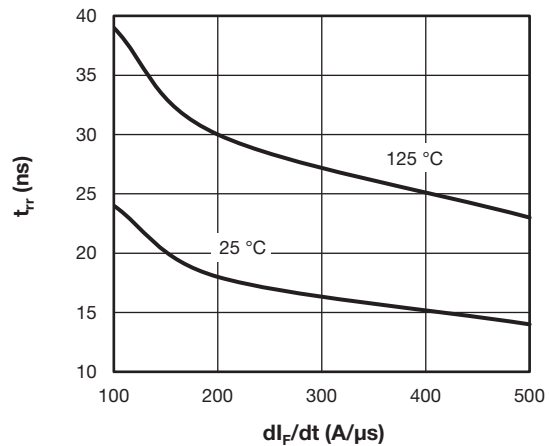


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

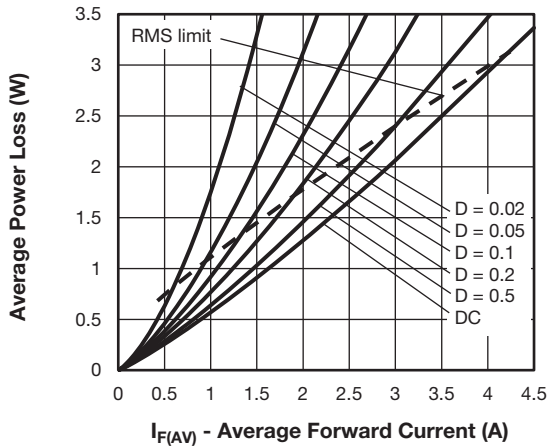


Fig. 6 - Forward Power Loss Characteristics

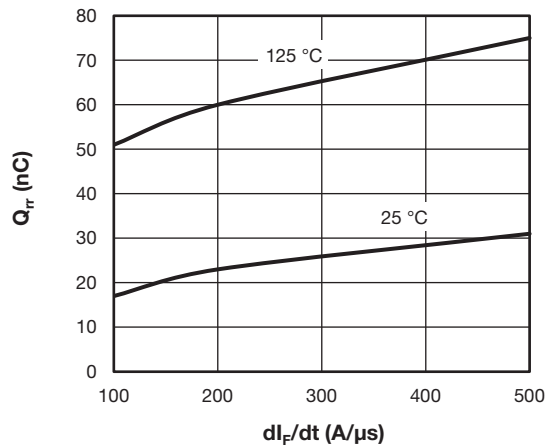


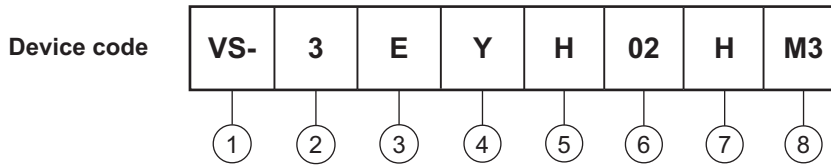
Fig. 8 - Typical Stored Charge vs. dI_F/dt

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$;
 P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 5);
 $P_{d_{REV}}$ = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (3 = 3 A)
- 3** - Circuit configuration:
E = single diode
- 4** - Y = SlimSMAW (DO-221AD)
- 5** - Process type,
H = hyperfast recovery
- 6** - Voltage code (02 = 200 V)
- 7** - H = AEC-Q101 qualified
- 8** - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	PACKAGING DESCRIPTION
VS-3EYH01HM3/H	0.033	H	3500	7" diameter plastic tape and reel
VS-3EYH01HM3/I	0.033	I	14 000	13" diameter plastic tape and reel
VS-3EYH02HM3/H	0.033	H	3500	7" diameter plastic tape and reel
VS-3EYH02HM3/I	0.033	I	14 000	13" diameter plastic tape and reel

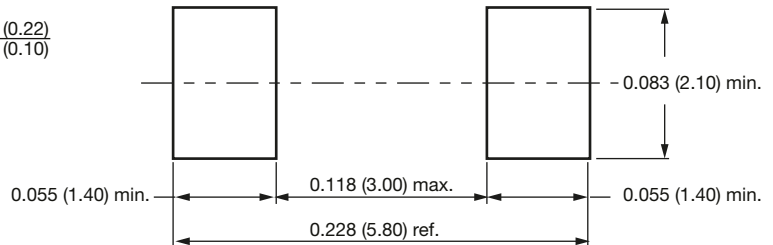
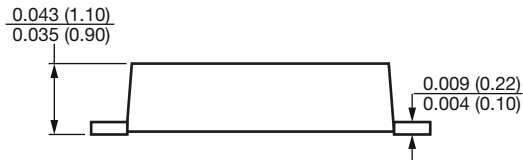
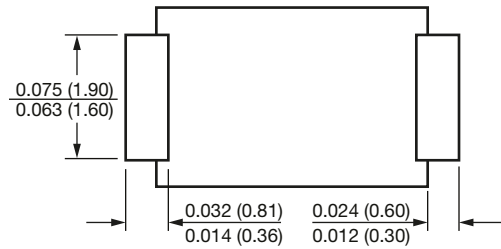
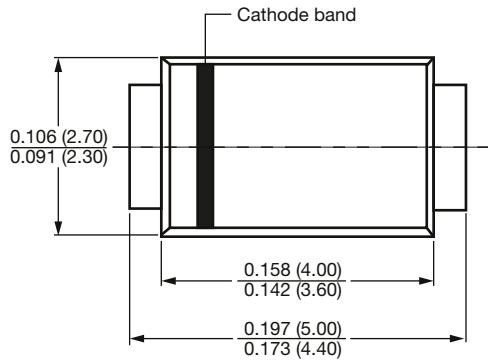
LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96582
Part marking information	www.vishay.com/doc?95562
Packaging information	www.vishay.com/doc?88869
SPIICE model	www.vishay.com/doc?96586



SlimSMAW (DO-221AD)

DIMENSIONS in inches (millimeters)

SlimSMAW (DO-221AD)



Mounting pad layout



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